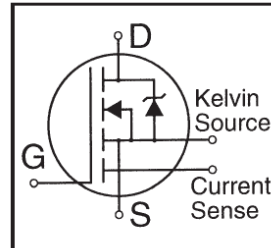


IRCZ44PbF

HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Current Sense
- 175°C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

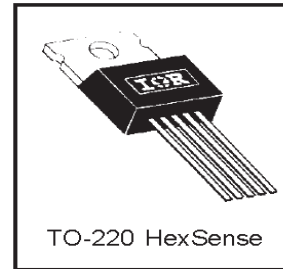


$V_{DSS} = 60V$
$R_{DS(on)} = 0.028\Omega$
$I_D = 50*A$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device, low on-resistance and cost-effectiveness.

The HEXSense device provides an accurate fraction of the drain current through the additional two leads to be used for control or protection of the device. These devices exhibit similar electrical and thermal characteristics as their IRF-series equivalent part numbers. The provision of a kelvin source connection effectively eliminates problems of common source inductance when the HEXSense is used as a fast, high-current switch in non current-sensing applications.



Absolute Maximum Ratings

Parameter		Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	50*	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	37	
I_{DM}	Pulsed Drain Current ①	210	
$P_D @ T_C = 25^\circ C$	Power Dissipation	150	W
	Linear Derating Factor	1.0	W/°C
V_{GS}	Gate-to-Source Voltage	±20	V
E_{AS}	Single Pulse Avalanche Energy ②	30	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.5	V/ns
T_J	Operating Junction and	-55 to + 175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1 N•m)	

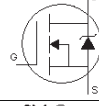
Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	1.0	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient —	—	—	62	

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	60	---	---	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	---	0.060	---	V/°C	Reference to 25°C , $I_D = 1mA$
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	---	---	0.028	Ω	$V_{GS} = 10V, I_D = 31A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	2.0	---	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
g_{fs}	Forward Transconductance	18	---	---	S	$V_{DS} = 25V, I_D = 31A$
I_{DSS}	Drain-to-Source Leakage Current	---	---	25		$V_{DS} = 60V, V_{GS} = 0V$
		---	---	250		$V_{DS} = 48V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	---	---	100		$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	---	---	-100		$V_{GS} = -20V$
Q_g	Total Gate Charge	---	---	95		$I_D = 52A$
Q_{gs}	Gate-to-Source Charge	---	---	27	nC	$V_{DS} = 48V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	---	---	46		$V_{GS} = 10V$, See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	---	19	---		$V_{DD} = 30V$
t_r	Rise Time	---	120	---		$I_D = 52A$
$t_{d(off)}$	Turn-Off Delay Time	---	55	---		$R_G = 9.1\Omega$
t_f	Fall Time	---	86	---		$R_D = 0.54\Omega$, See Fig. 10 ④
L_D	Internal Drain Inductance	---	4.5	---	nH	Between lead, 6 mm (0.25in.) from package and center of die contact
L_C	Internal Source Inductance	---	7.5	---		
C_{iss}	Input Capacitance	---	2500	---		$V_{GS} = 0V$
C_{oss}	Output Capacitance	---	1200	---	pF	$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	---	200	---		$f = 1.0MHz$, See Fig. 5
r	Current Sensing Ratio	2460	---	2720	---	$I_D = 52A, V_{GS} = 10V$
C_{oss}	Output Capacitance of Sensing Cells	---	9.0	---	pF	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	---	---	50*	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	---	---	210		
V_{SD}	Diode Forward Voltage	---	---	2.5	V	$T_J = 25^\circ\text{C}, I_S = 52A, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	---	140	300	ns	$T_J = 25^\circ\text{C}, I_F = 52A$
Q_{rr}	Reverse Recovery Charge	---	1.2	2.8	nC	$di/dt = 100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

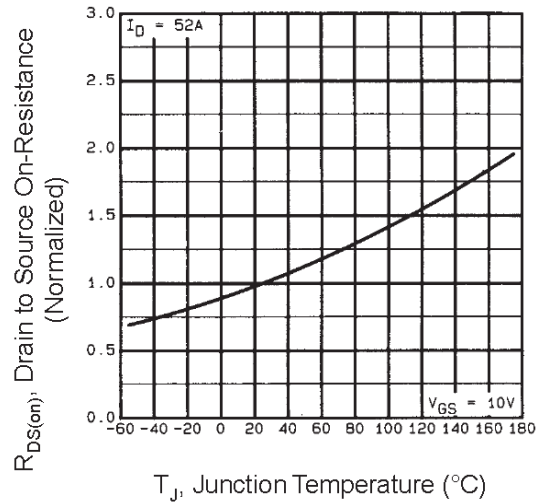
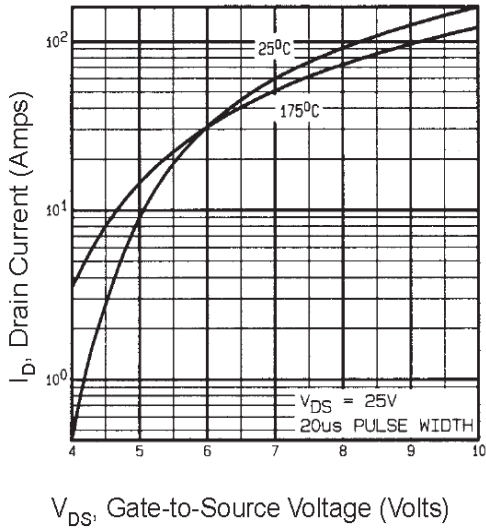
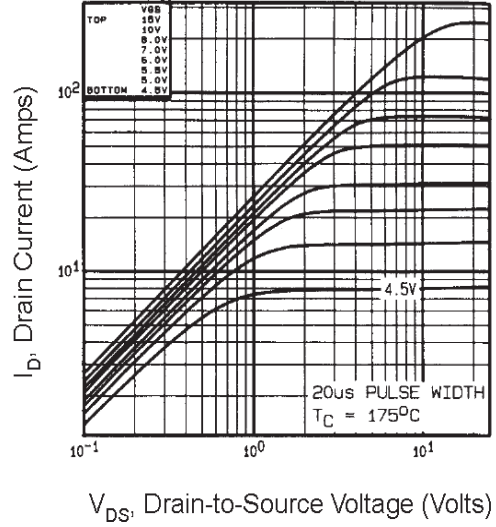
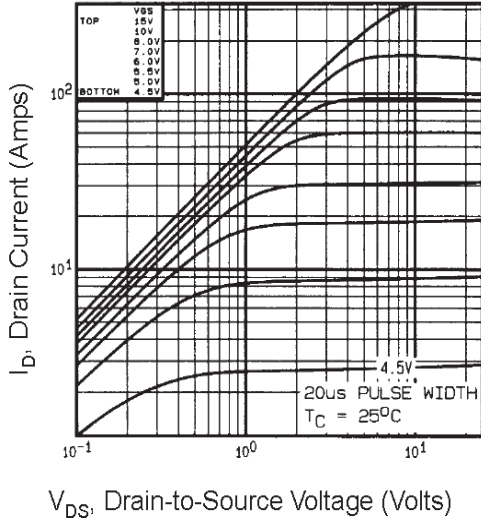
Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

③ $I_{SD} \leq 52A, di/dt \leq 250A/\mu s, V_{DD} \leq V_{(BR)DSS}, T_J \leq 175^\circ\text{C}$

② $V_{DD} = 25V, \text{ starting } T_J = 25^\circ\text{C}, L = 0.013mH, R_G = 25\Omega, I_{AS} = 52A.$ (See Figure 12)

④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.



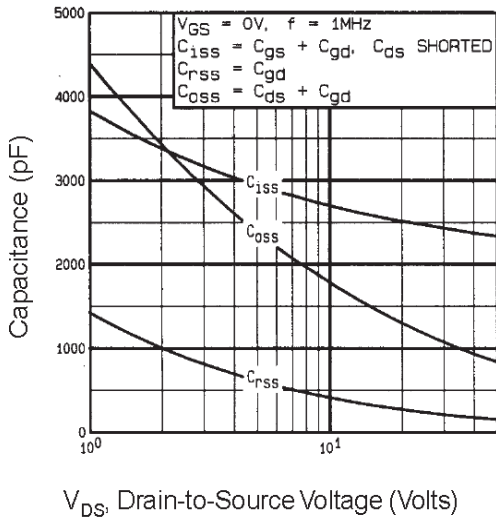


Fig. 5 Typical Capacitance vs. Drain-to-Source Voltage

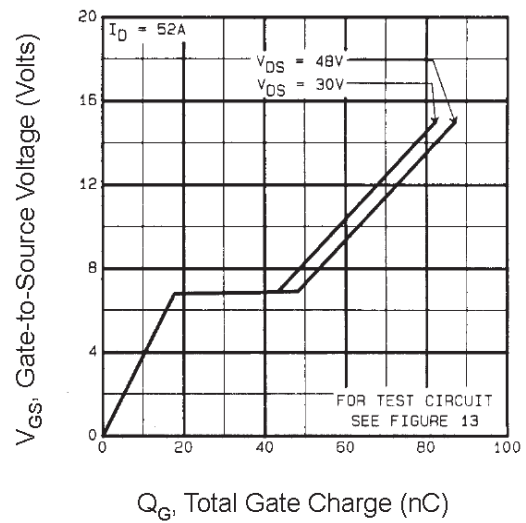


Fig. 6 Typical Gate Charge vs. Gate-to-Source Voltage

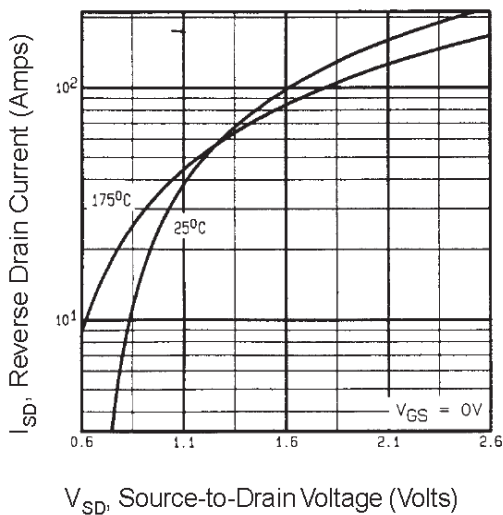


Fig. 7 Typical Source-Drain Diode Forward Voltage

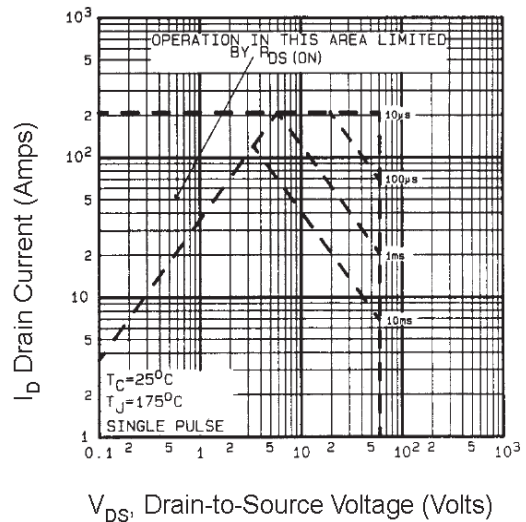


Fig. 8 Maximum Safe Operating Area

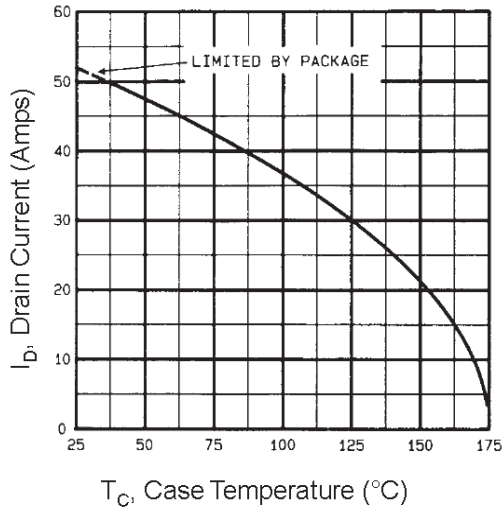


Fig. 9 Maximum Drain Current vs. Case Temperature

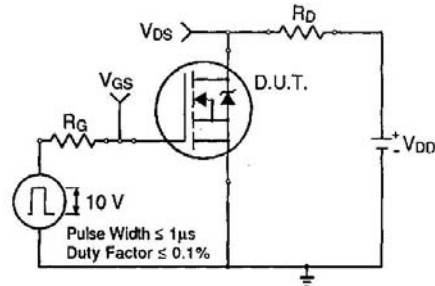


Fig 10a. Switching Time Test Circuit

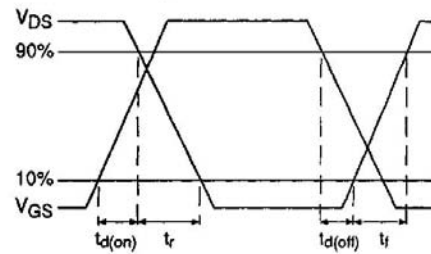


Fig 10b. Switching Time Waveforms

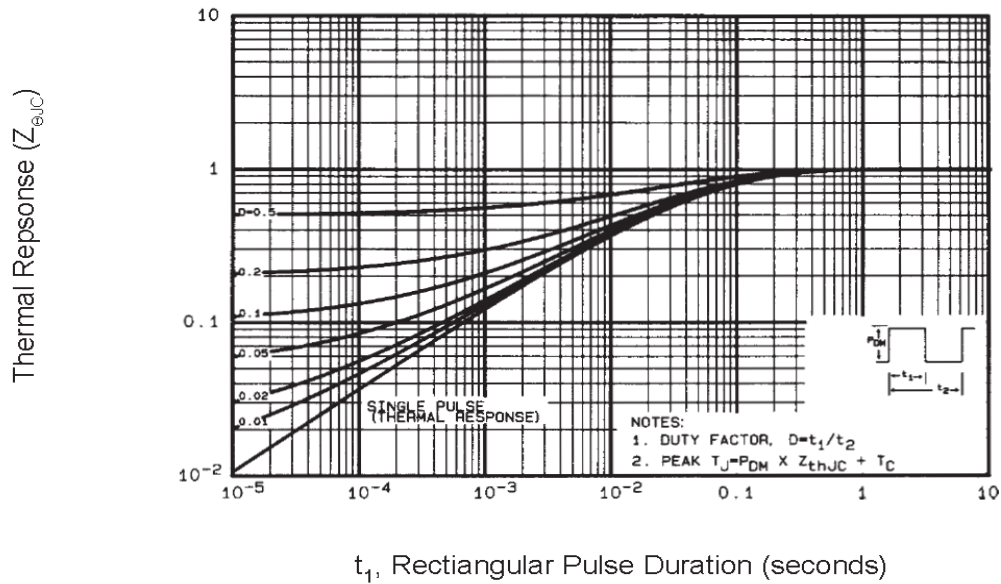


Fig. 11 Maximum Effective Transient Thermal Impedance, Junction-to-Case

IRCZ44PbF

International
IR Rectifier

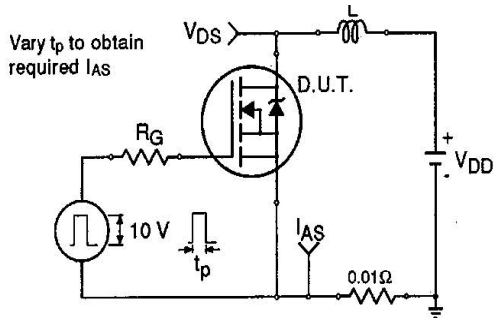


Fig 12a. Unclamped Inductive Test Circuit

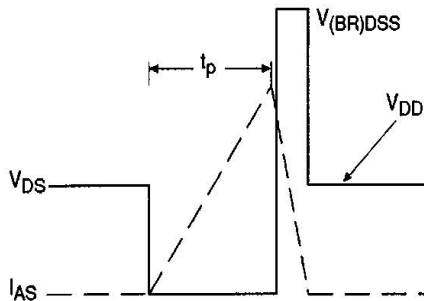


Fig 12b. Unclamped Inductive Waveforms

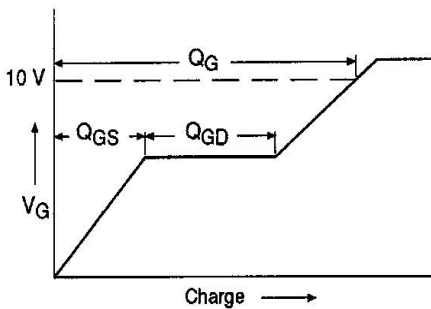


Fig 13a. Basic Gate Charge Waveform

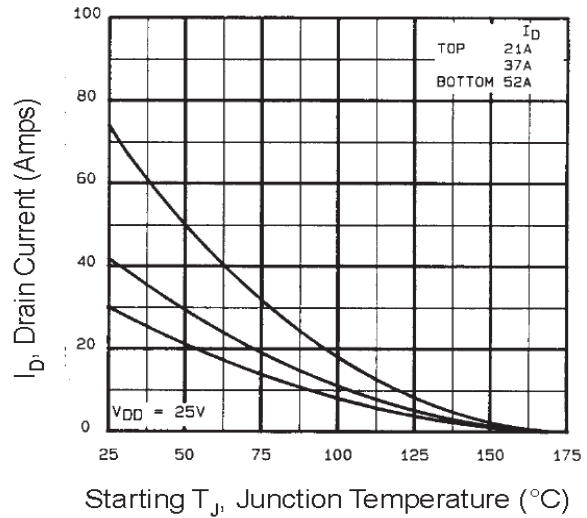


Fig. 12c Maximum Avalanche Energy vs. Drain Current

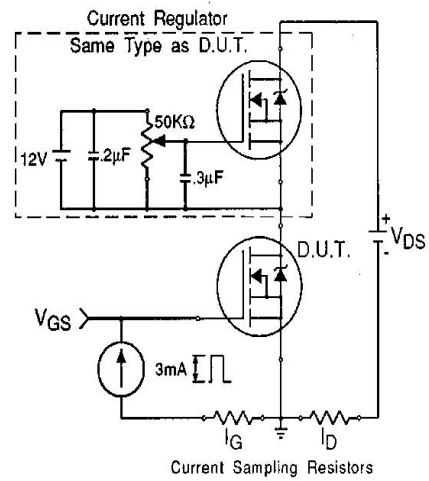


Fig 13b. Gate Charge Test Circuit

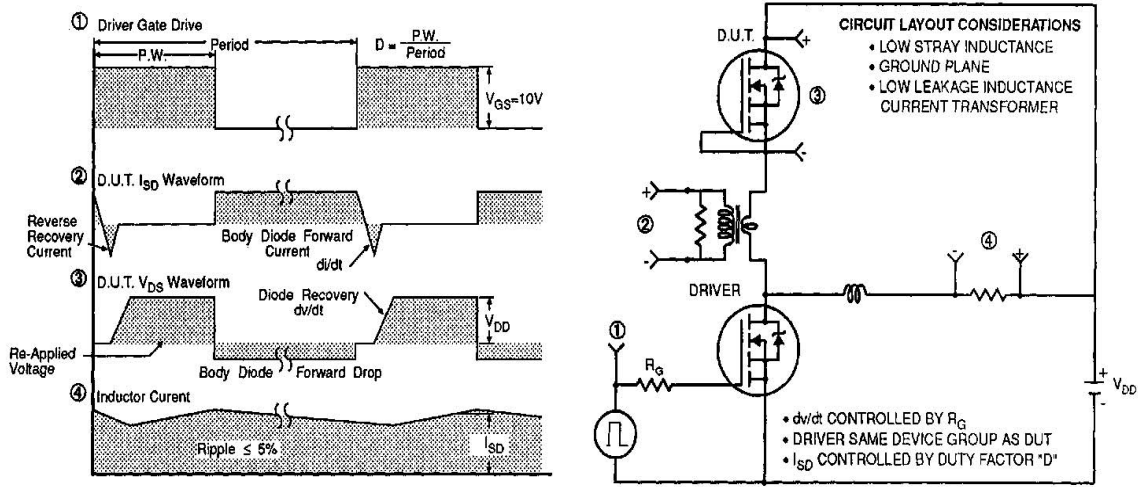


Fig 14. Peak Diode Recovery dv/dt Test Circuit

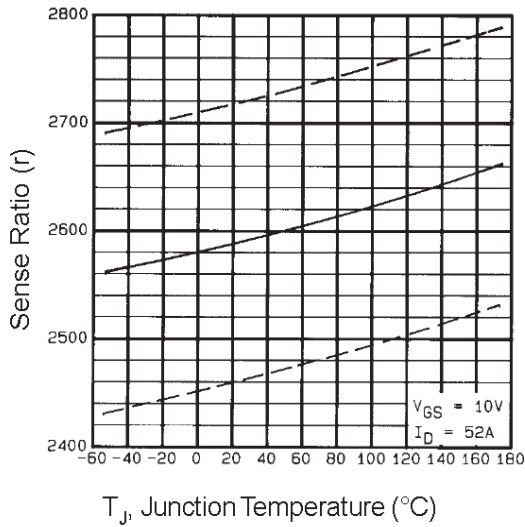


Fig. 15 Typical HEXSense Ratio vs. Junction Temperature

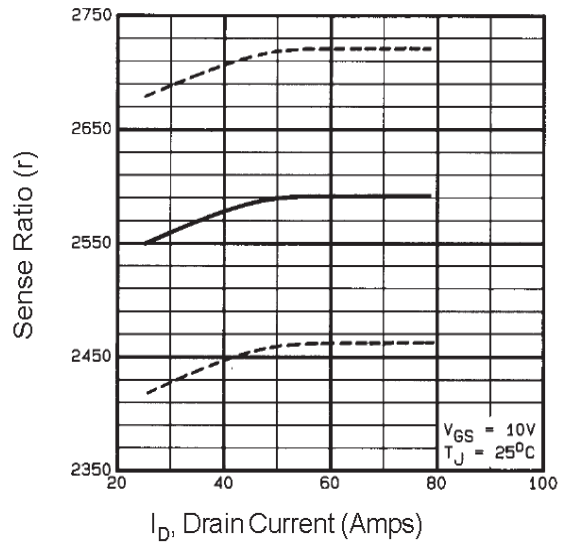


Fig. 16 Typical HEXSense Ratio vs. Drain Current

IRCZ44PbF

International
IR Rectifier

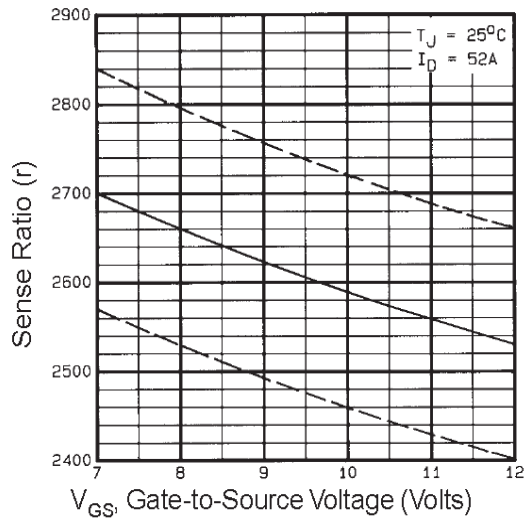


Fig. 17 Typical HEXSense Ratio vs. Gate Voltage

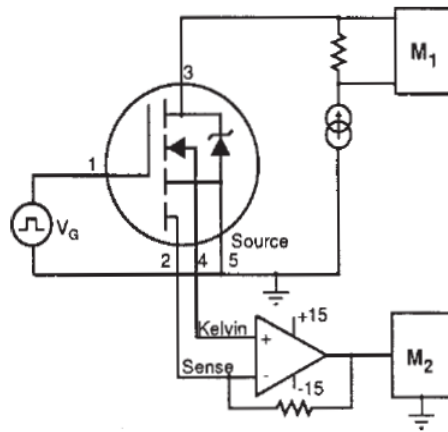


Fig. 18 HEXSense Ratio Test Circuit

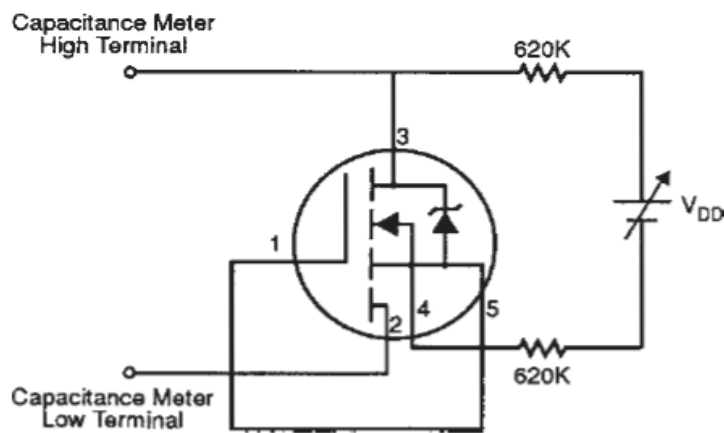
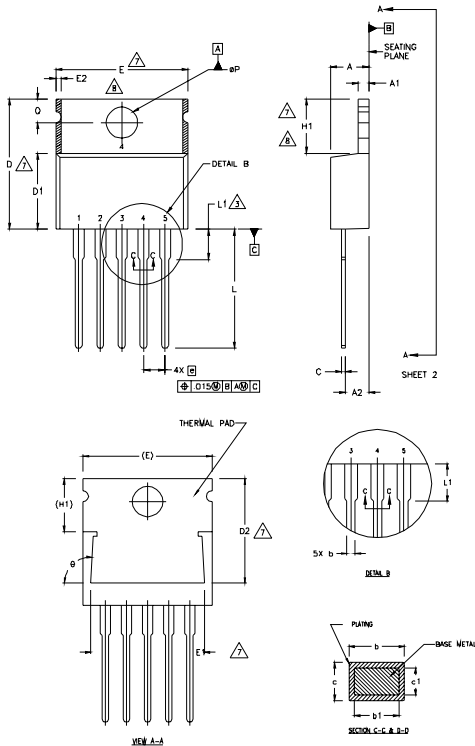


Fig. 19 HEXSense Sensing Cell Output Capacitance Test Circuit

HexsenseTO-220 5L Package Outline

(Dimensions are shown in millimeters (inches))



NOTES:

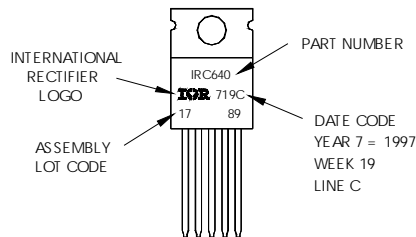
- 1 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- 2 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- 3 LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
- 4 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 5 DIMENSION b1 & c1 APPLY TO BASE METAL ONLY.
- 6 CONTROLLING DIMENSION : INCHES.
- 7 THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
- 8 DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	3.56	4.82	.140	.190	
A1	0.51	1.40	.020	.055	
A2	2.04	2.92	.080	.115	
b	0.64	0.88	.025	.035	
b1	0.64	0.84	.025	.033	5
c	0.36	0.61	.014	.024	
c1	0.36	0.56	.014	.022	5
D	14.22	16.51	.560	.650	4
D1	8.38	9.02	.330	.355	
D2	12.19	12.88	.480	.507	7
E	9.66	10.66	.380	.420	4,7
E1	8.38	8.89	.330	.350	7
e	1.70 BSC		.067 BSC		
H1	5.85	6.55	.230	.270	7,8
L	13.47	14.09	.530	.555	
L1	-	6.35	-	.250	3
ØP	3.54	4.08	.139	.161	
Q	2.54	3.42	.100	.135	
Ø	90°-93°		90°-93°		

Hexsense TO-220 5L Part Marking Information

EXAMPLE: THIS IS AN IRC640
 WITH ASSEMBLY
 LOT CODE 1789
 ASSEMBLED ON WW19, 1997
 IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position
 indicates "Lead-Free"



Data and specifications subject to change without notice.